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# Product Change Notification - GBNG-08VONE361 (Convert To PDF)

#### Date:

10 Aug 2018

# **Product Category:**

Linear Regulators; Power MOSFET Drivers; Temperature Sensors; Linear Regulator **ICs** 

## Affected CPNs:





# **Notification subject:**

CCB 3450 and 3450.001 Initial Notice: Qualification of GTBF as a new assembly site in selected products of 6um, 0.6um AMI, 0.6um TSMC, 42K, 130K,133K, and BIC1 Supertex wafer technologies available in 3L and 5L TO-220 packages.

### **Notification text:**

#### **PCN Status:**

Initial notification

#### **PCN Type:**

Manufacturing Change

## **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

# **Description of Change:**

Qualification of GTBF as a new assembly site in selected products of 6um, 0.6um AMI, 0.6um TSMC, 42K, 130K,133K, and BIC1 Supertex wafer technologies available in 3L and 5L TO-220 packages.

#### **Pre Change:**

Assembled at CARM using 84-1 LMISR4 or 2815A die attach, CEL-9240HF10 molding compound and HCL-12S lead frame material.

# **Post Change:**

Assembled at GTBF using CRM-1800 die attach, EME-G600 molding compound and LY80 lead frame material.

## **Pre and Post Change Summary:**

	Pre Ch	ange	Post Change				
Assembly Site	Carsem (M) (CAR		Great Team Backend Foundry (Dong Guan) Ltd. (GTBF)				
Wire material	Αι	1	Au				
Die attach material	84-1 LMISR4	2815A	CRM-1800				
Molding compound material	CEL-924	0HF10	EME-G600				
Lead frame material	HCL-	125	LY80				

# **Impacts to Data Sheet:**

None

## **Change Impact:**

None

#### **Reason for Change:**

To improve on-time delivery performance by qualifying GTBF as a new assembly site. CARM assembly site will no longer have manufacturing support for the selected products.

# **Change Implementation Status:**

In Progress

# **Estimated Qualification Completion Date:**

October 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

# **Time Table Summary:**

	August 2018					$\rightarrow$	October 2018				
Workweek	31	32	33	34	35		40	41	42	43	44
Initial PCN Issue Date		Х									

Qual Report Availability				Х		
Final PCN Issue Date				X		

## **Method to Identify Change:**

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

#### **Revision History:**

August 10, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN\_GBNG-08VONE361\_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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